505861887 01/13/2020

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5908824

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chin-Chun Huang	01/10/2020
Yun-Pin Teng	01/10/2020
JINJIAN OUYANG	01/10/2020
WEN YI TAN	01/10/2020

RECEIVING PARTY DATA

Name: United Semiconductor (Xiamen) Co., Ltd.	
Street Address: NO.899 Wan Jia Chun Road, Xiamen Xiang'an	
City:	Xiamen, Fujian
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16741698

CORRESPONDENCE DATA

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using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	NAUP3548USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	01/13/2020

Total Attachments: 8

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Title of Invention: RRAM STRUCTURE AND METHOD OF FABRICATING THE SAME

As the below named inventor, I hereby dec This declaration is directed to:	are that:		
☑ The attached application, or			
☐ United States application number	fil	led on,	or
☐ PCT international application num	ıber	filed on	anoner comments
The above-identified application was made	or authorized to be made by	me.	
I believe that I am the original inventor or a application.	an original joint inventor of a cl	aimed invention in the	
I hereby acknowledge that any willful false under18 U.S.C. 1001 by fine or imprisonm			
	ed Semiconductor (Xiam Ltd.	nen) having a postal add	ress of
NO.899 Wan Jia Chun Road, Xiam	en Xiang'an, Xiamen, Fuj	jian 361100, P.R.C.	
(referred to as "ASSIGNEE"below) to I of t acknowledged, andfor other good and value		, the receipt of which is he	reby
I hereby sell, assign and transfer to ASSIG the entire right, title and interest in and to a invention as above-identified application a invention by the above application or any o substitutes, or extensions thereof, and as	any and all improvements whic nd, in and to, all Letters Paten continuations, continuation-in-	ch are disclosed in the nt to be obtained for said part, divisions, renewals,	EE
I hereby covenant that no assignment, sal entered into which would conflict with this		e has been or will be made	or
I further covenant that ASSIGNEE will, up and documents relating to said invention a known and accessible to I and will testify a related thereto and will promptly execute a	and said Letters Patent and leg as to the same in any interfere	gal equivalents as may be ence, litigation proceeding	ets
representatives any and all papers, instruit maintain, issue and enforce said application equivalents thereof which may be necessary IN WITNESS WHEREOF, I have hereunted	on, said invention and said Let ary or desirable to carry out the	tters Patent and said e proposes thereof.	
Note: An application data sheet (PTO/SB/inventive entity, must accompany this form			

Page 1 of 8

NPO#NAU-P3548-USA:0 CUST#UMCX-2019-0014

Docket No NAUP3548USA

LEGAL NA	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Chin-Chun Huang	Date:	JAN 1 0 2028	
Signature:	Chin, Chun Huang			
			and the second s	

NPO#NAU-P3548-USA:0

CUST#UMCX-2019-0014

Page 2 of 8

Title of Invention:

RRAM STRUCTURE AND METHOD OF FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:				
☑ The attached application, or					
☐ United States application nu	mber	filed	d on	, or	
☐ PCT international application	n number	f	iled on		
The above-identified application was	made or authorized	to be made by me	э.		
I believe that I am the original invent application.	or or an original joint	inventor of a clair	ned invention ir	the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				e	
In consideration of the payment by	United Semicond Co., Ltd.	luctor (Xiame	n) having a po	ostal address o	of
NO.899 Wan Jia Chun Road,	Xiamen Xiang'an,	Xiamen, Fujia	n 361100, P.	R.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are			ne receipt of wh	ich is hereby	
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, an	nd to any and all impr ition and, in and to, al r any continuations, c	ovements which I Letters Patent to ontinuation-in-pa	are disclosed in to be obtained for t, divisions, ren	n the or said newals,	
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I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exercise.	ntion and said Letters estify as to the same i	Patent and legal n any interference	equivalents as e, litigation proc	may be	
representatives any and all papers, maintain, issue and enforce said appequivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said inventic ecessary or desirable	n and said Letter to carry out the p	rs Patent and sa proposes thereo	f.	
Note: An application data sheet (PT					

Page 3 of 8

NPO#NAU-P3548-USA:0 CUST#UMCX-2019-0014

LEGAL NAME	OF	INVENT	OR	(ASSI	GNOR	ď
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Inventor: Yun-Pin Teng

Date:

JAN 1 0 2020

Signature:

Tun-Pin Teng

NPO#NAU-P3548-USA:0

CUST#UMCX-2019-0014

ge 4 of

F#NPO-P0002E-US1201 DSB0-108U036072

Title of Invention:

RRAM STRUCTURE AND METHOD OF FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	ımber	filed on	, or
☐ PCT international application	n number	filed on	
The above-identified application was	s made or authorized to be ma	de by me.	
I believe that I am the original inventapplication.	tor or an original joint inventor	of a claimed invention in the	
I hereby acknowledge that any willfuunder18 U.S.C. 1001 by fine or impr	Il false statement made in this risonment of not more than five	declaration is punishable (5) years, or both.	
In consideration of the payment by	United Semiconductor Co., Ltd.	(Xiamen) having a postal	address of
NO.899 Wan Jia Chun Road,	Xiamen Xiang'an, Xiame	n, Fujian 361100, P.R.C	· ·•
(referred to as "ASSIGNEE"below) t acknowledged, andfor other good ar		1.00), the receipt of which is	s hereby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, a	nd to any and all improvement ation and, in and to, all Letters r any continuations, continuati	ts which are disclosed in the Patent to be obtained for sai on-in-part, divisions, renewa	id ils,
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representatives any and all papers, maintain, issue and enforce said ap equivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said invention and sa ecessary or desirable to carry	aid Letters Patent and said out the proposes thereof.	
Note: An application data sheet (PT inventive entity, must accompany th			

Page 5 of 8

NPO#NAU-P3548-USA:0 CUST#UMCX-2019-0014

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: JINJIAN OUYANG

Date:

JAN 1 0 2020

Signature:

JEW JEAN DUYANG

Page 6 of 8

F#NPO-P0002E-US1201 DSB0-108U036072

NPO#NAU-P3548-USA:0 CUST#UMCX-2019-0014

Title of Invention:

RRAM STRUCTURE AND METHOD OF FABRICATING THE SAME

As the below named inventor, I herel This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nur	mber	filed on,	or
☐ PCT international application	number	filed on	
The above-identified application was	made or authorized to be made	e by me.	
I believe that I am the original inventor application.	or or an original joint inventor of	a claimed invention in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made in this described in this described in the five (eclaration is punishable 5) years, or both.	
In consideration of the payment by	United Semiconductor (X Co., Ltd.	(iamen) having a postal addr	ess of
NO.899 Wan Jia Chun Road, X	(iamen Xiang'an, Xiamen,	Fujian 361100, P.R.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	I of the sum of One Dollar (\$ 1 d valuable consideration.	.00), the receipt of which is here	eby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	d to any and all improvements ion and, in and to, all Letters P any continuations, continuation	which are disclosed in the atent to be obtained for said annuals.	Ε
I hereby covenant that no assignmen entered into which would conflict with	t, sale, agreement or encumbra this assignment;	ance has been or will be made o	or
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters Patent and stify as to the same in any inter	d legal equivalents as may be ference, litigation proceeding	S
representatives any and all papers, ir maintain, issue and enforce said app equivalents thereof which may be ne- IN WITNESS WHEREOF, I have her	lication, said invention and said cessary or desirable to carry ou	Letters Patent and said	
Note: An application data sheet (PTC inventive entity, must accompany this	0/SB/14 or equivalent), including s form. Use this form for <u>each a</u>	naming the entire	

Page 7 of 8

NPO#NAU-P3548-USA:0 CUST#UMCX-2019-0014

Docket No NAUP3548USA

LEGAL NA	ME OF INVENTOR(ASSI	ENOR)				
Inventor:	WEN YI TAN		Date:	JAN 1	0 2020	
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F#NPO-P0002E-US1201 DSB0-108U036072

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